

ML610400 Series

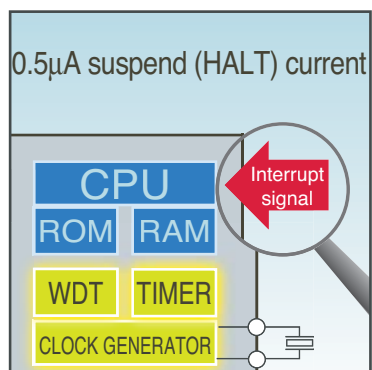
Ver.1.1



Key Features

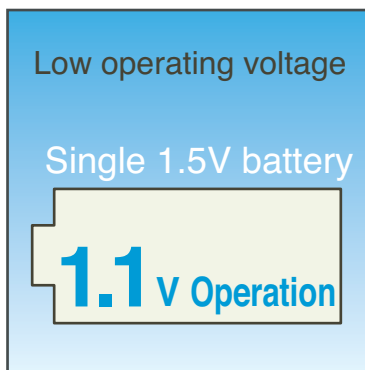
Feature 1

Low current consumption
prolongs battery life



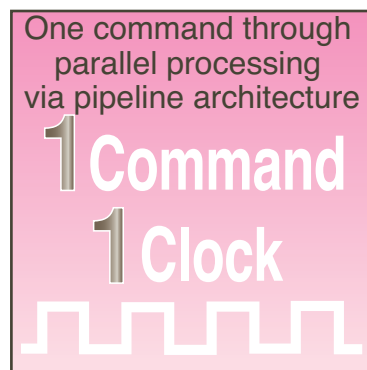
Feature 2

Low voltage operation
contributes to smaller
system size



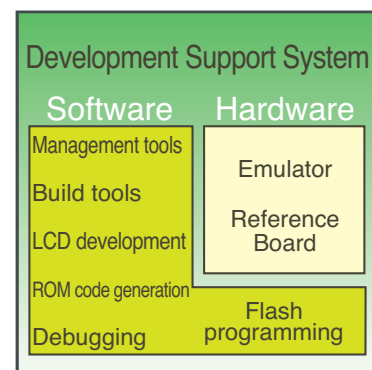
Feature 3

High performance CPU core
reduces system power
requirements



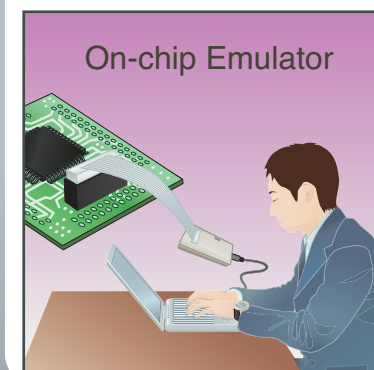
Feature 4

Comprehensive
development environment



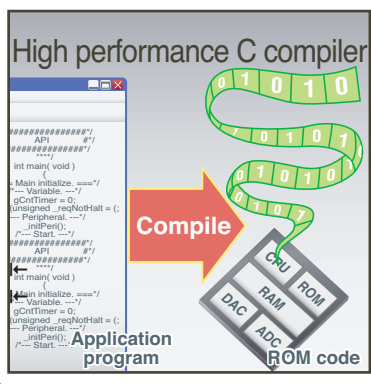
Feature 5

Simple, easy-to-use debugger
and on-chip emulator



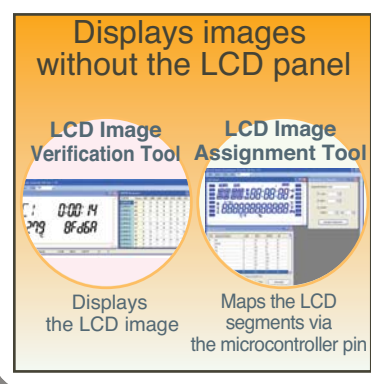
Feature 6

Software development with
code-efficient C compiler



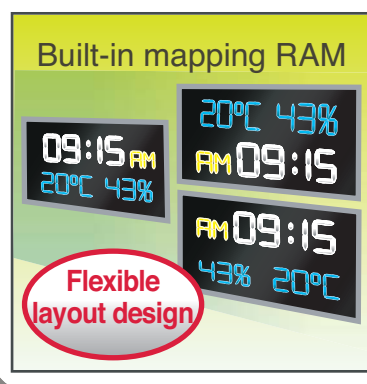
Feature 7

LCD tool simplifies
LCD control program
development



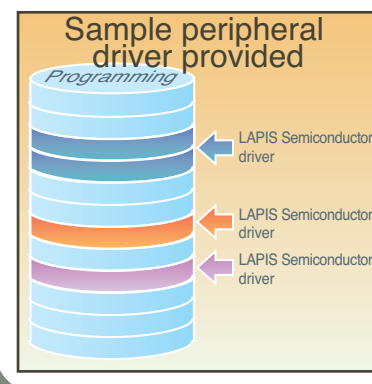
Feature 8

Troublesome software
changes no longer required
when changing the LCD panel



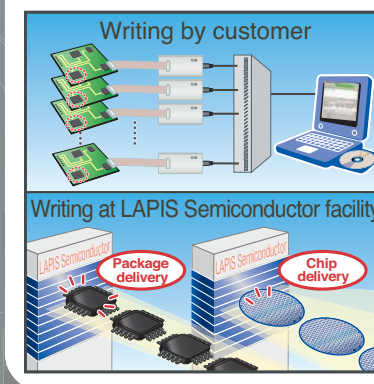
Feature 9

Multiple sample peripheral
drivers provided
for easy integration



Feature 10

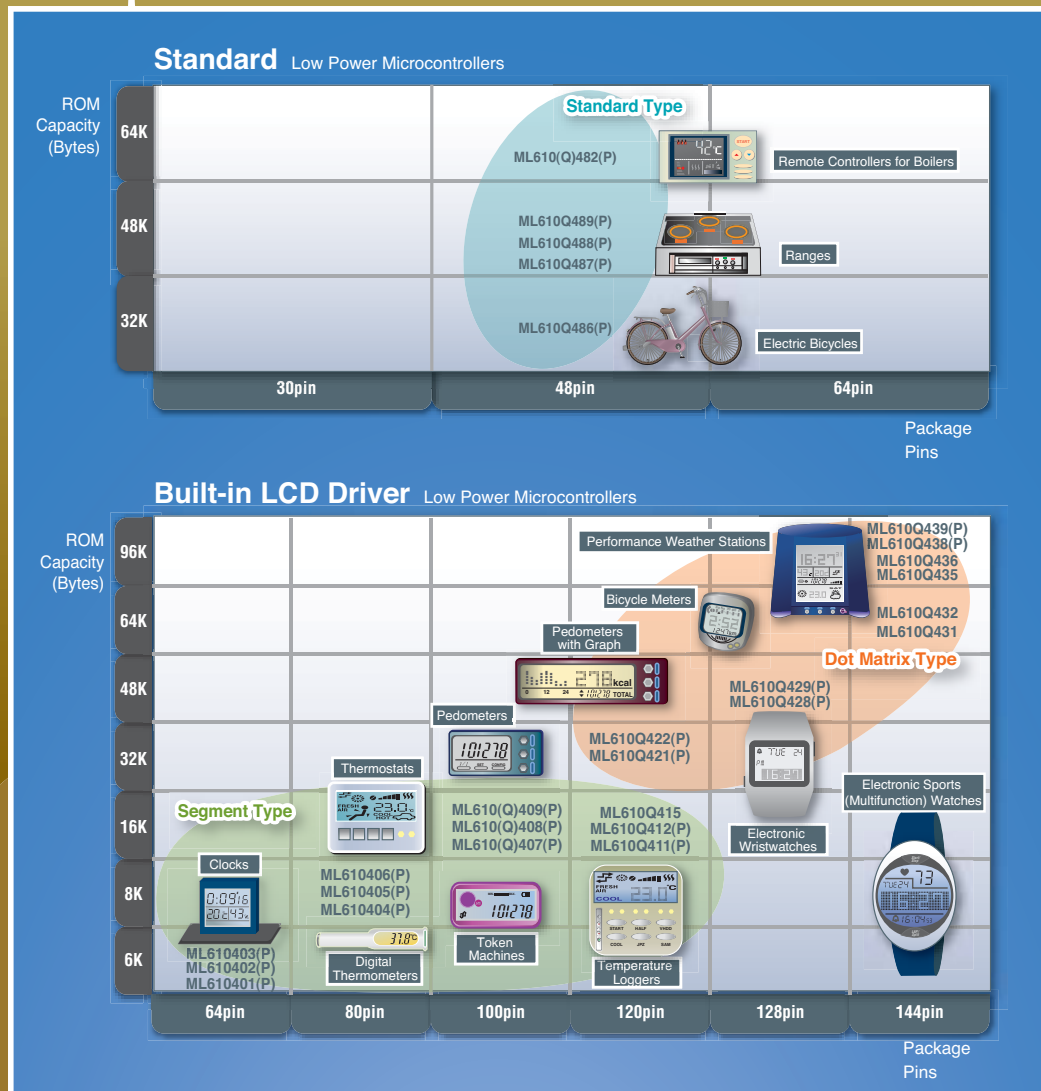
Flexible writing process



ML610400 Series Overview

This series is equipped with Flash memory for application code storage readable at only 1.1V and features industry-leading operating, halt, and sleep current consumption. In addition, a high performance CPU core is included, capable of processing one instruction per clock cycle. The result is high performance and ultra-low power consumption. Pin- and function-compatible Mask ROM models are also offered featuring identical characteristics. The products can be delivered in either packaged or die format. Customers can also opt to have programming performed by LAPIS Semiconductor as part of the standard manufacturing process or at their site using a multiwriter.

Lineup



Standard Low power microcontrollers

These low power microcontrollers are ideal for compact, battery-driven systems without an LCD.

- Program memory (32KByte to 64KByte), RAM (1KByte to 4KByte)
- Low speed clock : 32.768kHz, High-speed clock : 500kHz to 4.096MHz
- 3 types of serial communication ports (I²C, SSIO, UART)
- 8bit / 16bit Timer, 16bit PWM
- Available in bare die / TQFP48 package formats



Built-in Dot Matrix LCD Driver Low power microcontrollers

These low power microcontrollers integrate a boost circuit for driving LCDs, eliminating the need for an external LCD power supply.

- Supports 400 to 1536 dot LCDs (1/24 to 1/2 duty, 1/4 to 1/3 bias)
- 32-128KByte program memory, 2 to 7KByte RAM
- Low speed clock : 32.768kHz, High-speed clock : 500kHz to 4.096MHz
- 2 A/D converters (24bit RC oscillation, 12bit successive approximation)
- Integrated LCD display allocation RAM and LCD drive voltage step-up circuit
- Available in bare die / TQFP120 to LQFP144 package formats



Built-in Segment LCD Driver Low power microcontrollers

These low power microcontrollers with segment LCD driver integrates a boost circuit for driving an LCD.

- Supports 55 to 185 segment LCDs (1/5 to 1/2 duty, 1/3 to 1/2 bias)
- 6 to 16KByte program memory, 192Byte to 1KByte RAM
- Low speed clock : 32.768kHz, High-speed clock : 500kHz to 2MHz
- 16bit or 24bit RC oscillation type A/D converter for temperature / humidity measurement
- 12bit successive approximation type A/D converter
- Integrated LCD display allocation RAM and LCD drive voltage step-up circuit
- Available in bare die / TQFP64 to LQFP120 package formats

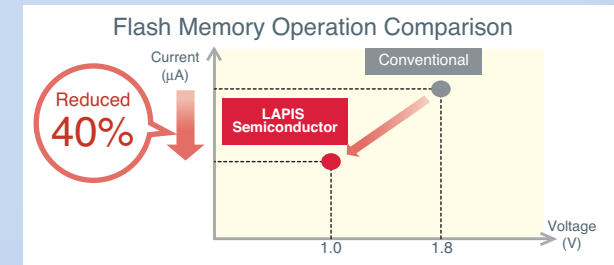
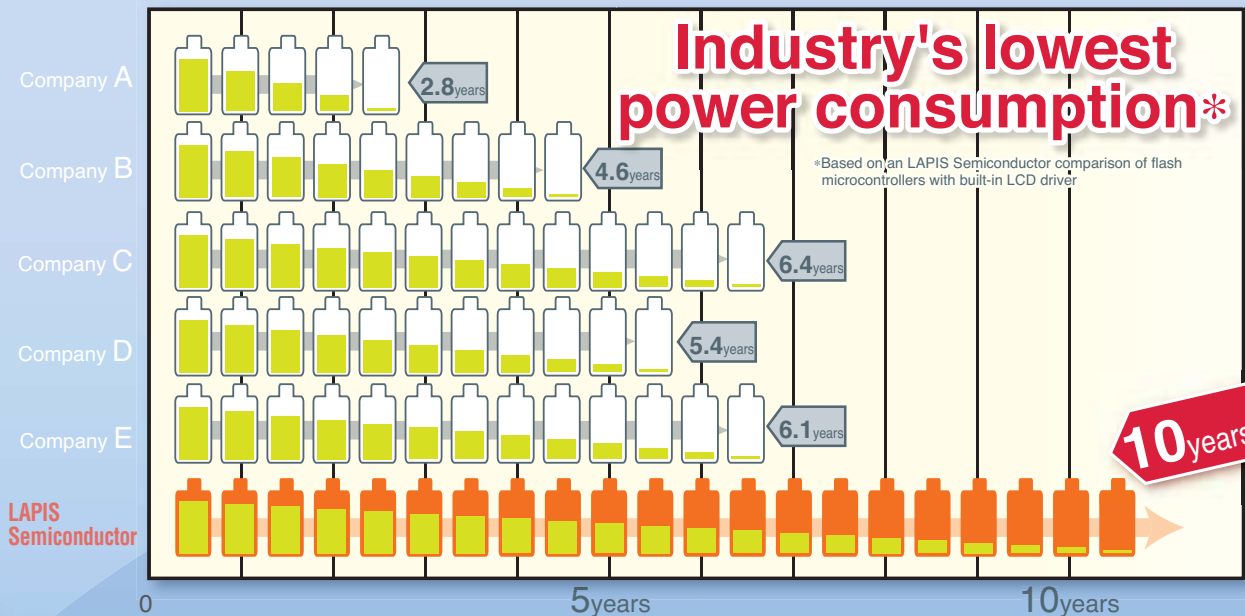
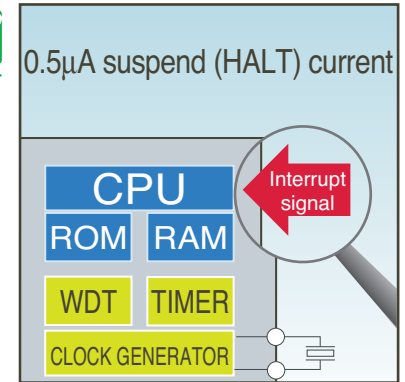


Feature 1

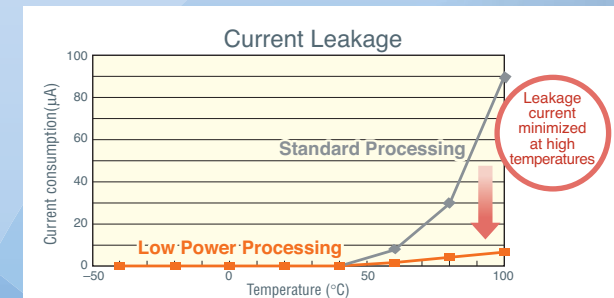
Low current consumption prolongs battery life

10 years on 1 battery!
Low power microcontroller

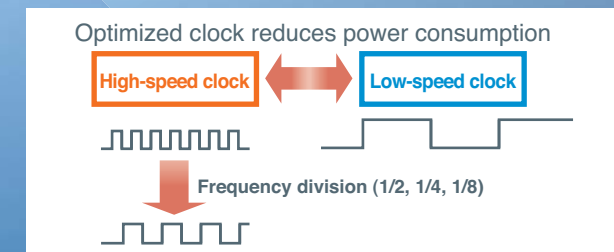
Original design technology and low power processes ensure low current consumption in all modes. In addition, a dual-clock system is utilized, enabling intermittent operation in low-power mode and selection of the optimum clock frequency, making operation possible for 10 years on just a single battery.



Unique process minimizes current leakage at high temperatures, reducing power consumption over a wider range.



Internal Flash memory capable of reading at only 1.1V, enabling operation from a single 1.5V battery.



Optimum clock selected via control software.

LAPIS Semiconductor has achieved industry-leading low power consumption in all modes

Microcontroller with Built-In Flash Memory (ML610Q431)

- CPU Operation (Built-in 4MHz PLL oscillator: 800μA) → **180μA at 1MHz**
- CPU Operation (External 32kHz oscillator: 5μA) → **Only 5μA with crystal oscillation clock**
- CPU Operation (Built-in 500kHz RC oscillator: 70μA) → **Uses even less current at lower speeds**
- HALT Operation (32kHz crystal oscillator + RTC + WDT: 0.5μA) → **Timing at low current**
- STOP Operation (No oscillation: 0.15μA) → **Reduce current leakage**

Low voltage operation contributes to smaller system size

Only 1.1V is required, making operation possible using only a single 1.5V battery. This contributes to more compact, lightweight devices while reducing costs.

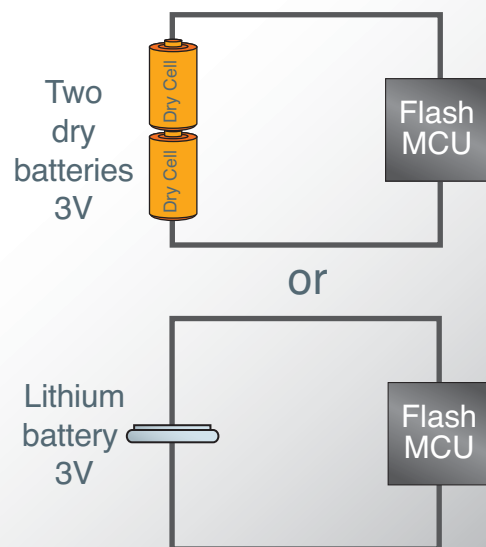
The low minimum operation voltage, combined with 32.768kHz crystal oscillation clock and extremely low current consumption (in low-power mode) results in longer battery life and enables the use of double layer capacitors for (a low-cost) backup.

Low operating voltage

Single 1.5V battery

1.1V Operation

Conventional Low Power Microcontroller



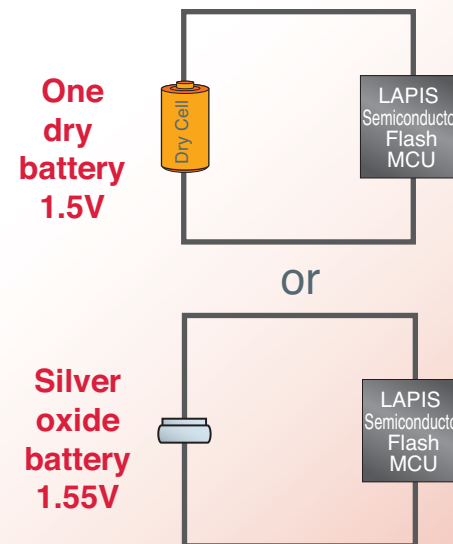
Typ.4500 μ W@500kHz, 3V

Lower costs

Smaller and lighter

Power consumption
97% down*

LAPIS Semiconductor Ultra Low Power Microcontroller



Typ.105 μ W@500kHz, 1.5V

*Compared with standard
LAPIS Semiconductor products



High performance CPU core reduces system power requirements

These 8bit microcontrollers feature one instruction per clock cycle operation and deliver high performance - comparable to 16bit microcontrollers. In addition, RISC-based processing utilizing a rich instruction set for efficient bit/multi-byte operation, combined with intermittent firmware operation, enable high-performance operation even at slow clock cycles for reduced CPU processing time and lower system power consumption.



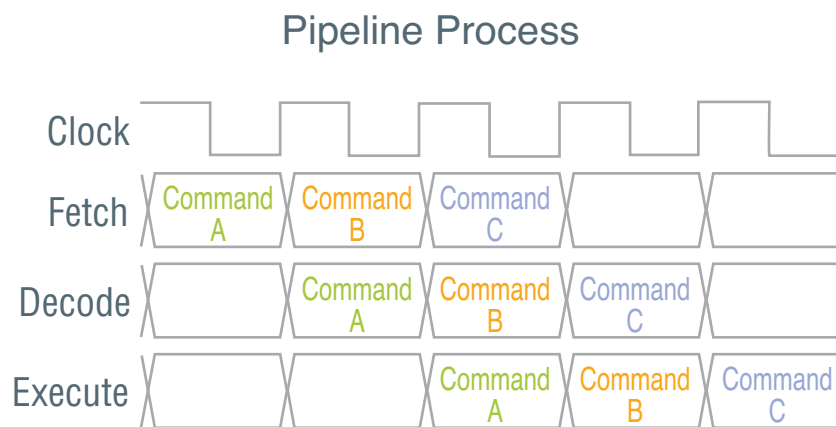
One command through parallel processing via pipeline architecture

1 Command
1 Clock

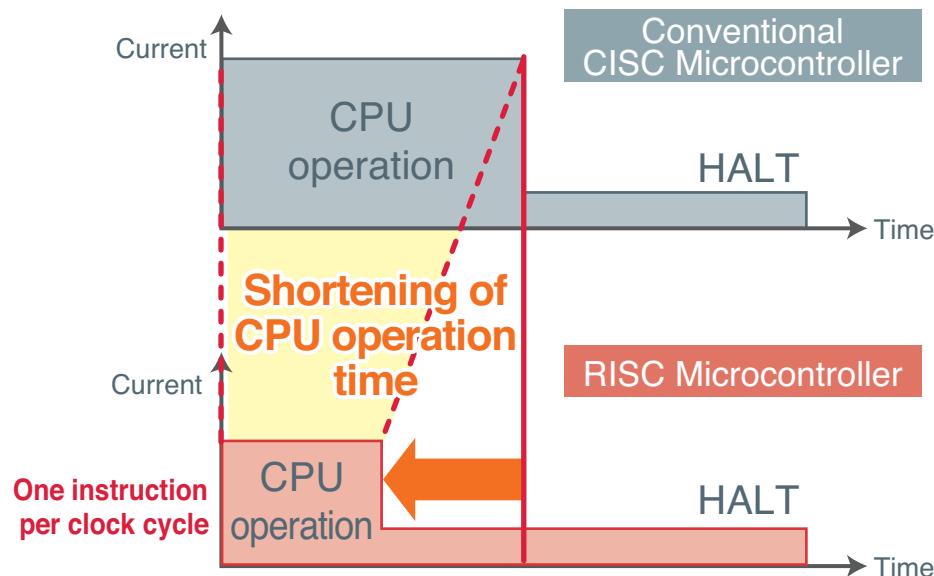


Minimum instruction execution time : **250ns@4MHz**
30.5μs@32.768kHz

Efficient CPU capable of processing one instruction per clock cycle



Command processing performed quickly before entering into standby mode



Comprehensive development environment



Support for all phases of software development is provided to the customer, from program builds, debugging, and Flash programming, to compact, lightweight on-chip debug emulators and reference boards with microcontrollers.

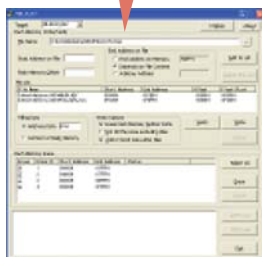
Build tool setup (Compiler, Assembler, and Linker) and debug tool setup (DTU8 debugger/simulator) are initiated in the integrated IDEU8 environment. The DTU8 debugger (running on a PC) is connected to the microcontroller through an on-chip debugger port controlled by a μ EASE debugger pod. The debugger controls and analyzes the execution of code on the microcontroller. The FW μ EASE Flash Writer and MW μ EASE Flash Multi-Writer are software tools used to write application code to the Flash memory. Multiple devices can be written to simultaneously. The LCD tools (part of the development suite), simulate LCD operation and provides several options for controlling an LCD.

Development Support System

Software Hardware

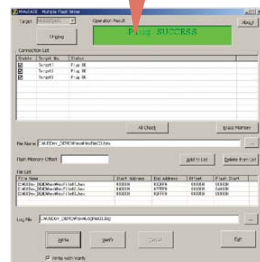
Management tools	Emulator
Build tools	Reference Board
LCD development	
ROM code generation	Flash programming
Debugging	

For debugging
(i.e. block erase,
address designation)



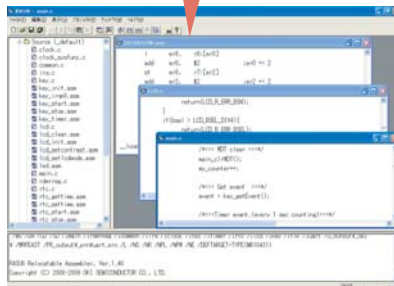
FW μ EASE Flash Writer with intuitive GUI

Simplifies writing to multiple devices
during mass production



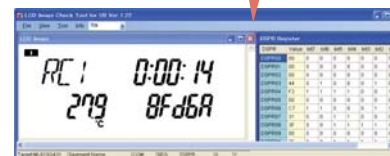
MW μ EASE Flash Multi-Writer offers simultaneous writing to up to 32 targets

Allows project management of multiple operations,
including header/source file
linking and C compiler/assembler/
linker option setting

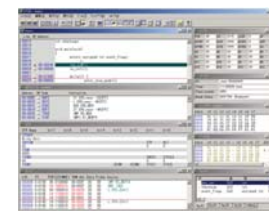


Integrated environment
IDEU8 incorporates development work
from program editing to build

Develop a display control program
without an actual LCD panel

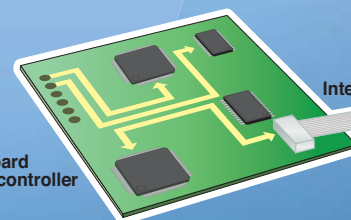


LCD image tool provides
LCD simulation



Enables source-level debugging,
including breakpoint setting
and step execution

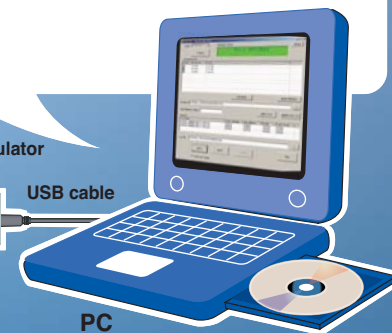
Simple, user-friendly DTU8 debugger



Reference Board
with Built-In Microcontroller

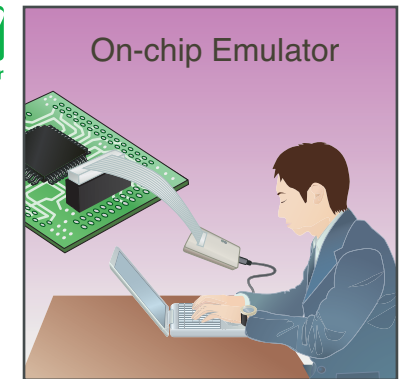
On-chip Debug Emulator
 μ EASE
Interface cable

USB cable



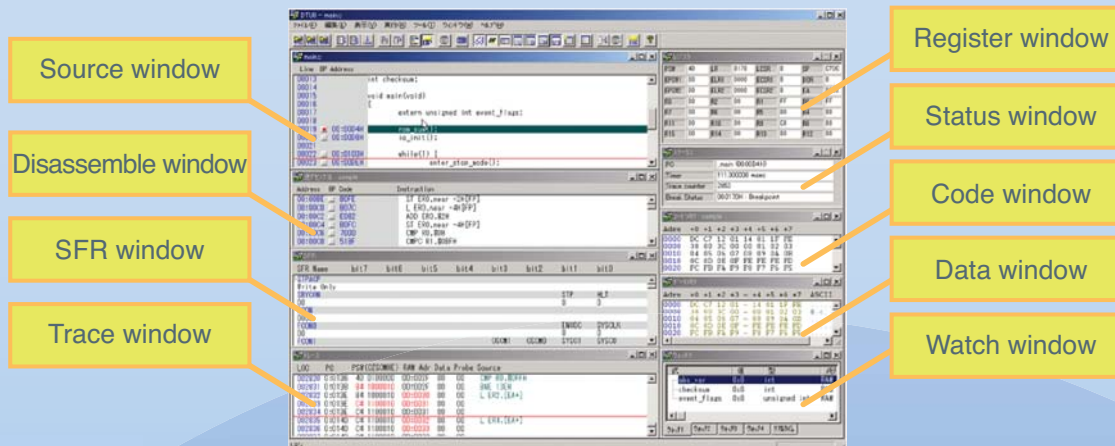
PC

Simple, easy-to-use debugger and on-chip emulator



The simple graphical user interface of the debugger is used to display multiple windows that contain a variety of information, such as C/assembly language, register data, and status. In addition, a single-step/subroutine function is included to check the behavior of the software one line (or subroutine) at a time. Enhanced break functions are also available that suspends software execution at a certain point in the code or to access a register or data location. Break functions are critical to real-time debugging and maximize system debugging performance.

DTU8 Debugger



Key Features of DTU8 / μ EASE

- Hardware break point enables pass count setting
- RAM data/address match break can detect data changes within a program
- Flash memory allows unlimited software break point settings
- Refer/register C language variables using the memory watch window



On-chip Debug Emulator μ EASE

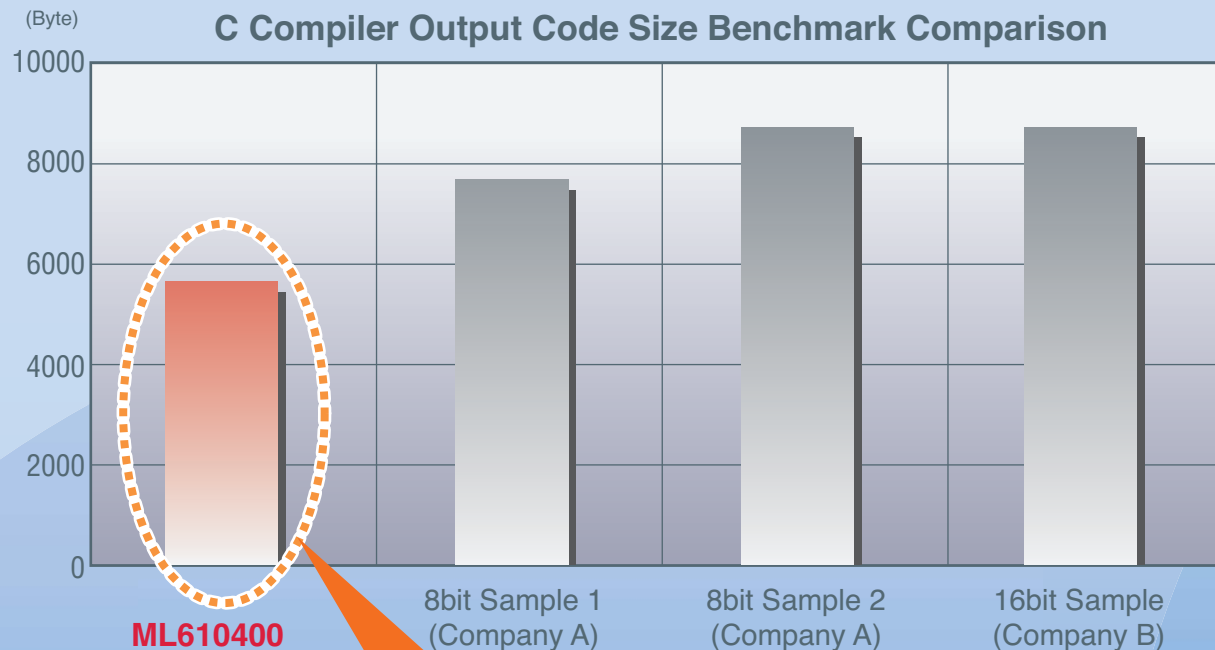
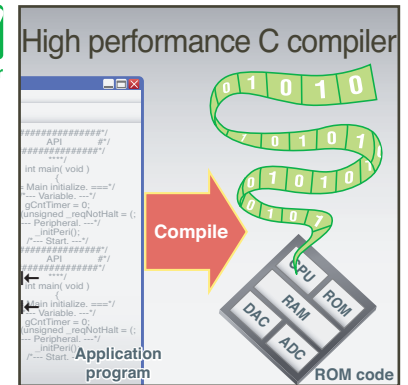
On-chip Debug Emulator μ EASE Specifications

Applicable devices	ML610400 series and other LSIs with on-chip debug functionality
Host interface	USB2.0 (High speed, Full speed)
Flash writing function	Program download to flash memory integrated in the target MCU (MCU with built-in flash memory)
Emulation function	Real-time emulation, Single step emulation
Break function	Hardware break points (program memory) : 3 points (2 points in source window, 1 point with address specification/counting function in another menu) RAM address data match break/counting function : 1 point Software break points : Entire program area (models with built-in flash memory only)
Memory / register control	Display/change the contents of program memory, data memory, general-purpose register, and SFR
Dimensions	50.0(W) $\times$ 90.0(D) $\times$ 9.0(H)
Weight	50g
Power supply	Supply from USB VBUS port

Software development with code-efficient C compiler

A high performance C compiler is utilized that minimizes ROM code and maximizes processing speed for optimum microcontroller operation. The 8bit CPU features a code efficiency equivalent to 16bit CPUs, resulting in the ideal program memory size.

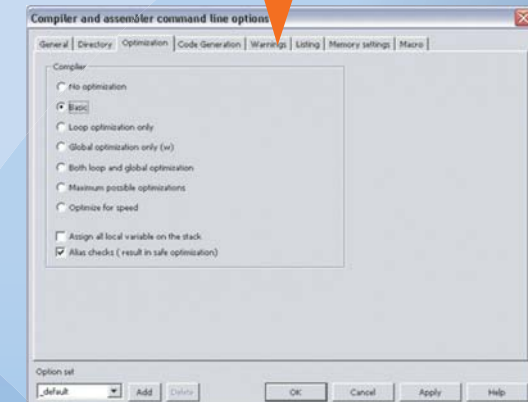
The CCU8 C compiler offers a variety of configurable options, such as optimization (minimizing program size and execution time of subroutines), setting the program stack size, and selecting the characteristics of the output files - including documentation for error checking. In addition, 'pragma' is available to handle interrupt processing routines and architecture-dependent functions for smooth development of application programs. The CCU8 C compiler is ANSI C language compliant, making it easy to port projects from other microcontrollers.



ML610400

Code-efficient 8bit MCU
comparable to 16bit MCU

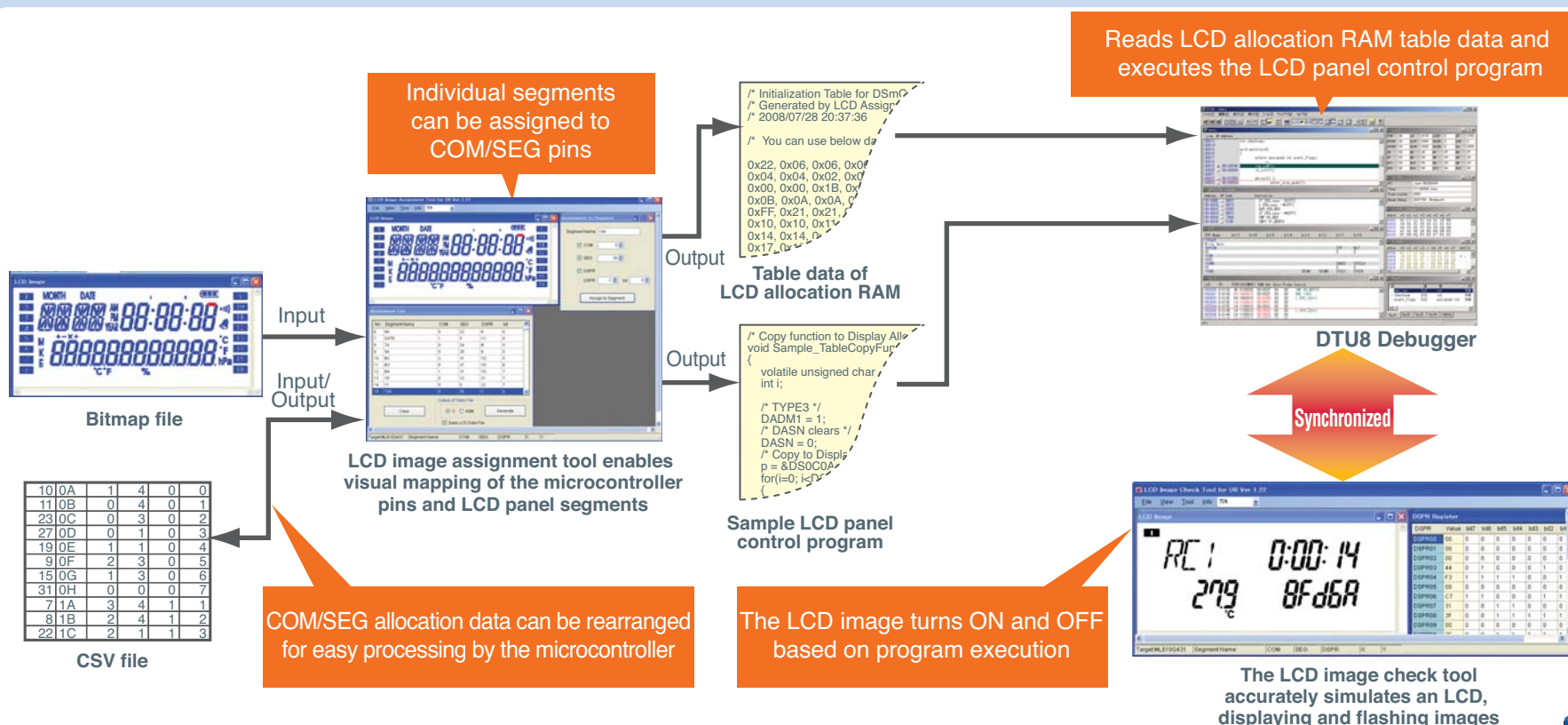
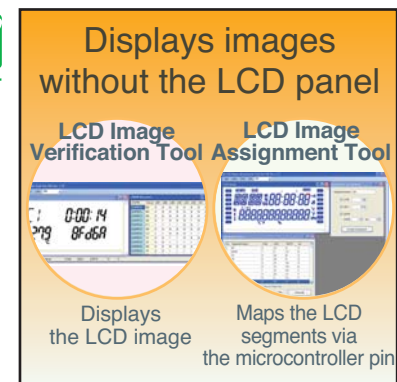
Numerous compiler options
maximize microcontroller performance



Option settings for the CCU8 C compiler

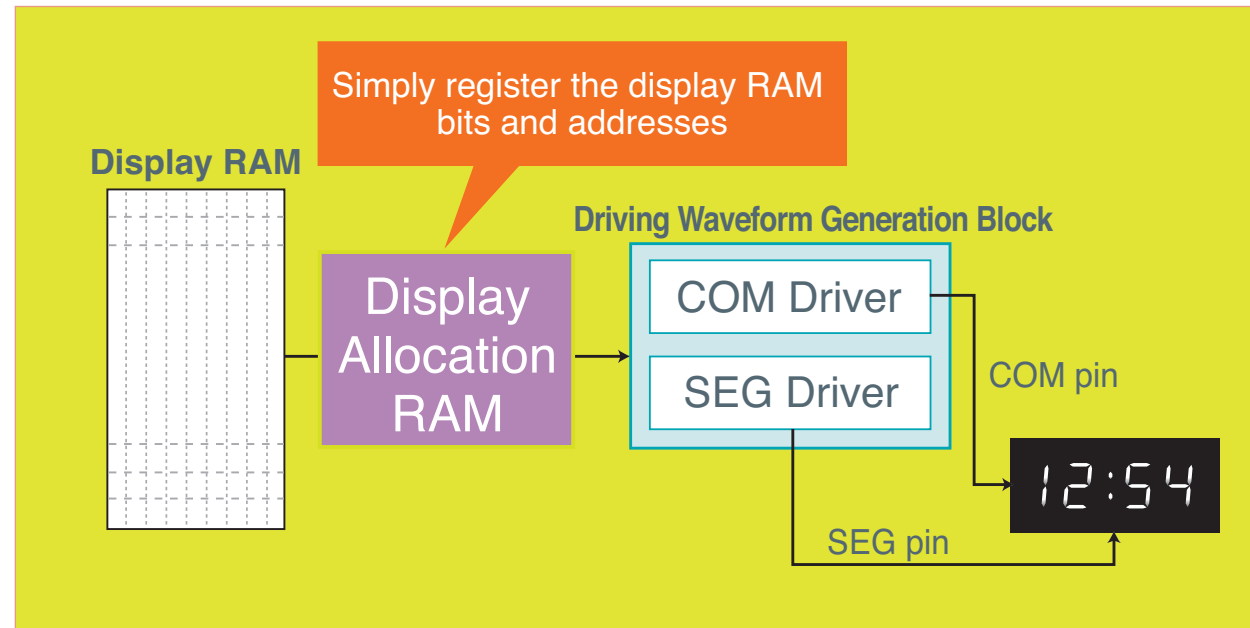
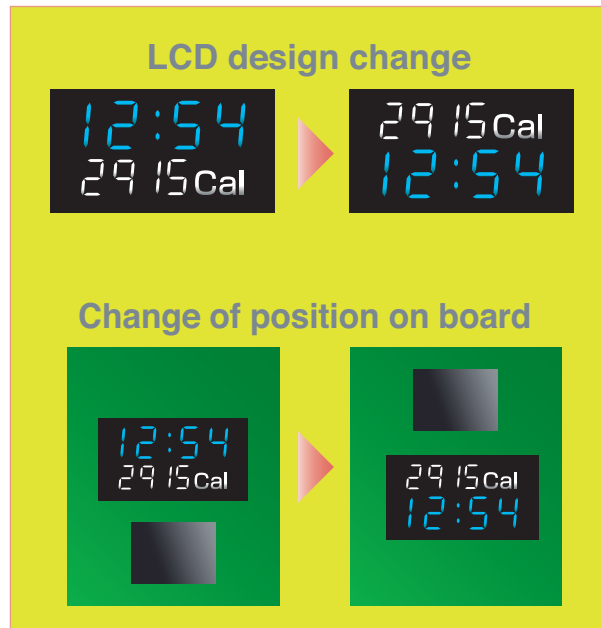
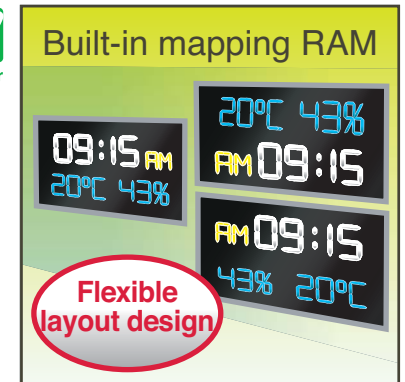
LCD tool simplifies LCD control program development

The LCD image tool includes an LCD image assignment tool and LCD image check tool. The LCD image assignment tool uses a bitmap file of the LCD and allows users to map the microcontroller COM and SEG pins to the LCD visually. It also automatically creates a data table for the LCD allocation RAM and LCD control program. The settings of the COM/SEG pins related to the LCD can be saved to or read from a CSV file to enhance work efficiency. The LCD image check tool can be used to check the operation of an LCD even without an LCD present. It simulates an LCD image on a PC based on the output of the simulator or while debugging in real time under the control of the DTU8 and μ EASE.



Troublesome software changes no longer required when changing the LCD panel

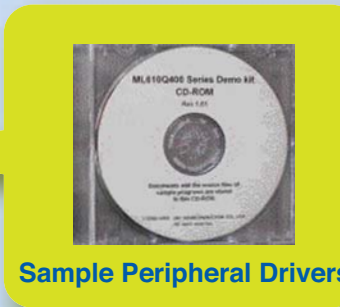
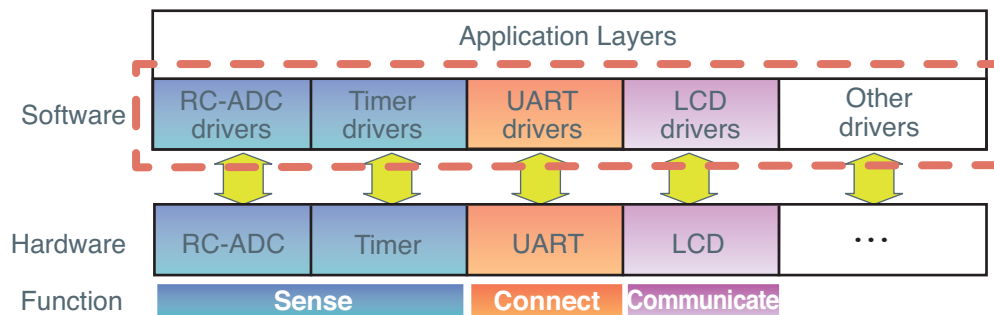
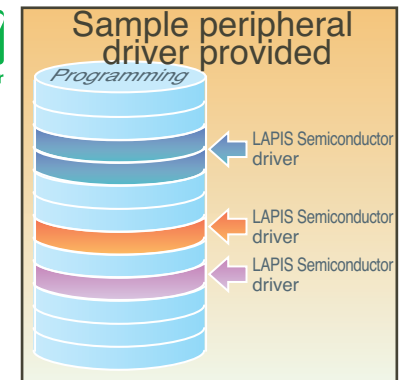
A display allocation RAM is integrated between the display RAM and COM/SEG pins that enables easy pin mapping. This feature is important when changing the pinout assignments of the display. Remapping an LCD is complicated and time-consuming and can take up to several days. However, this time can be shortened to only hours with display allocation RAM. Data creation and operation verification can also be performed by the LCD tools, facilitating user development.



**Requires only changes to the data settings in the display allocation RAM.
No complicated changes to display RAM control needed.**

Multiple sample peripheral drivers provided for easy integration

Sample drivers for configuring and operating peripheral circuits are provided to the the customer for application code development. These drivers are presented as software modules that allow the customer to integrate only those modules necessary, shortening development time considerably.

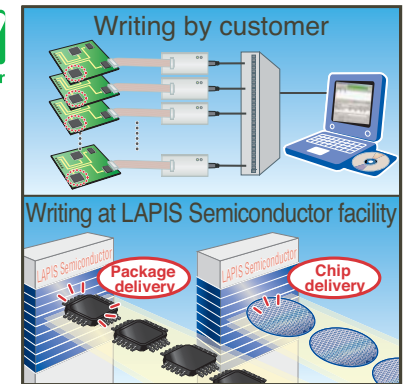


	Module Name	Functions
Sense	SA-ADC module	Initializes the successive approximation ADC module (i.e. conversion count, operating mode, secondary amp. settings), conversion start/stop, obtain conversion results, and measure the voltage
	RC-ADC module	Performs A/D conversion by digitalizing the ratio of the oscillation frequency between the reference resistor (or capacitor) and resistive sensor like thermistor (or capacitive sensor)
	Temperature calculation module	Calculates the temperature from the RC-ADC conversion results based on the thermistor 103AT frequency ratio - temperature conversion table
	Humidity calculation module	Calculates the humidity from the RC-ADC conversion results and measured temperature based on the C10-M53R humidity sensor frequency ratio (humidity ratio) - humidity conversion table
	Celsius ↔ Fahrenheit conversion module	Performs Celsius ↔ Fahrenheit conversion
	Air pressure calculation module	Calculates the barometric pressure by measuring the output of a bridge-type sensor (barometer) using the input of SA-ADC differential amplifier
	Real-time clock control module	Sets the counting function of the real-time clock
	Timer control module	Controls the 8bit/16bit timer operation
	Clock control module	Controls the clock (i.e. system clock settings)
	Time-based counter control module	Controls the high-speed time-based counter
	1kHz timer control module	Counts time (1/1000sec)
	Stopwatch module	Utilizes the 1kHz Timer Control Module to initialize the stopwatch and perform ON/OFF operation and data reading
Connect	UART module	Controls the UART (asynchronous serial interface)
	UART baud rate timer correction module	Measures the high-speed clock frequency in order to correct the UART baud rate timer value to maintain UART communication
	I ² C module	Controls the I ² C BUS interface (master)
	SSIO module	Controls the 8bit/16bit synchronous serial port (SSIO). It can be used to control a device with SPI interface when using one of the GPIO pins for chip enable
Communicate	EEPROM module	Performs EEPROM writing/reading via I ² C/SSIO
	LCD display module	Performs initialization (i.e. bias, duty, frame frequency), contrast/display mode setting, and 7SEG/16SEG display
	Key input module	Utilizes a port with interrupt function to perform initialization (input mode), key capture start/stop, and key event acquisition
	Melody module	Controls the melody/buzzer output of the melody driver
	BLD control module	Utilizes the battery level detection function to measure the MCU supply voltage

Flexible writing process

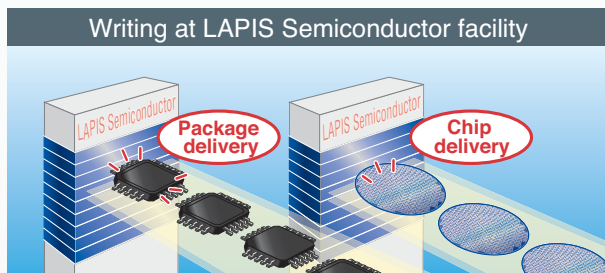
Users can opt for performing writing at their facility utilizing multi-writing software or at LAPIS Semiconductor's site, providing a greater level of flexibility.

Mass Production Method and Device Selection	Advantages/Disadvantages					Customer Responsibilities	LAPIS Semiconductor Responsibilities
	Reduced Writing Costs at the Customer's Site	Flexible, Comprehensive Testing at the Customer's Site	Prompt Response to Software Problems	Microcontroller Delivery	Microcontroller Unit Price		
Type 1 Writing to Flash ROM microcontrollers at LAPIS Semiconductor's facility	◎	△	△	○	△	Order ROM code products and provide the ROM code (software)	Deliver the Flash ROM products after writing the ROM code
Type 2 Writing to blank Flash ROM microcontrollers onboard and testing it at the customer's site	△	○	◎	◎	○	Order blanks, create a writing jig, and write the ROM code	Deliver blank Flash ROM products
Type 3 Writing to Flash ROM microcontrollers at LAPIS Semiconductor's facility then testing it onboard and performing final writing at the customer's site	△	◎	◎	○	△	Order ROM code products, provide the ROM code (software), create a writing jig, and write the ROM code	Deliver the Flash ROM products after writing the ROM code
Type 4 Manufacturing Mask ROM microcontrollers at LAPIS Semiconductor's facility (ES shipment included)	△	△	△	△	◎	Order ROM code products and provide the ROM code (software)	Deliver Mask ROM products after masking the ROM



Provides flexible support the customer's mass production process

Writing at LAPIS Semiconductor's facility



ROM Code Entry Format

ML610400 Series
Code Entry Confirmation



ML610400 Series
Checklist

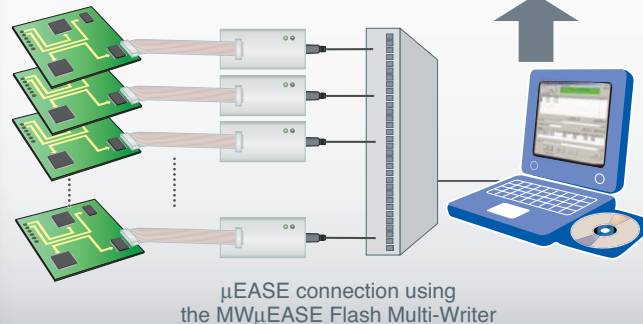


Mass Production
Certificate

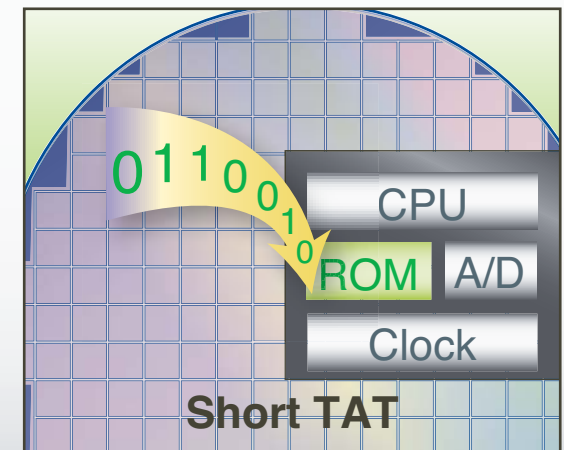


Writing by the customer using MWμEASE software

The MWμEASE Flash Multi-Writer
is capable of writing to up to
32 devices simultaneously



Chip writing and shipment also available





Standard Type ML610Q482 / ML610Q482P

Package



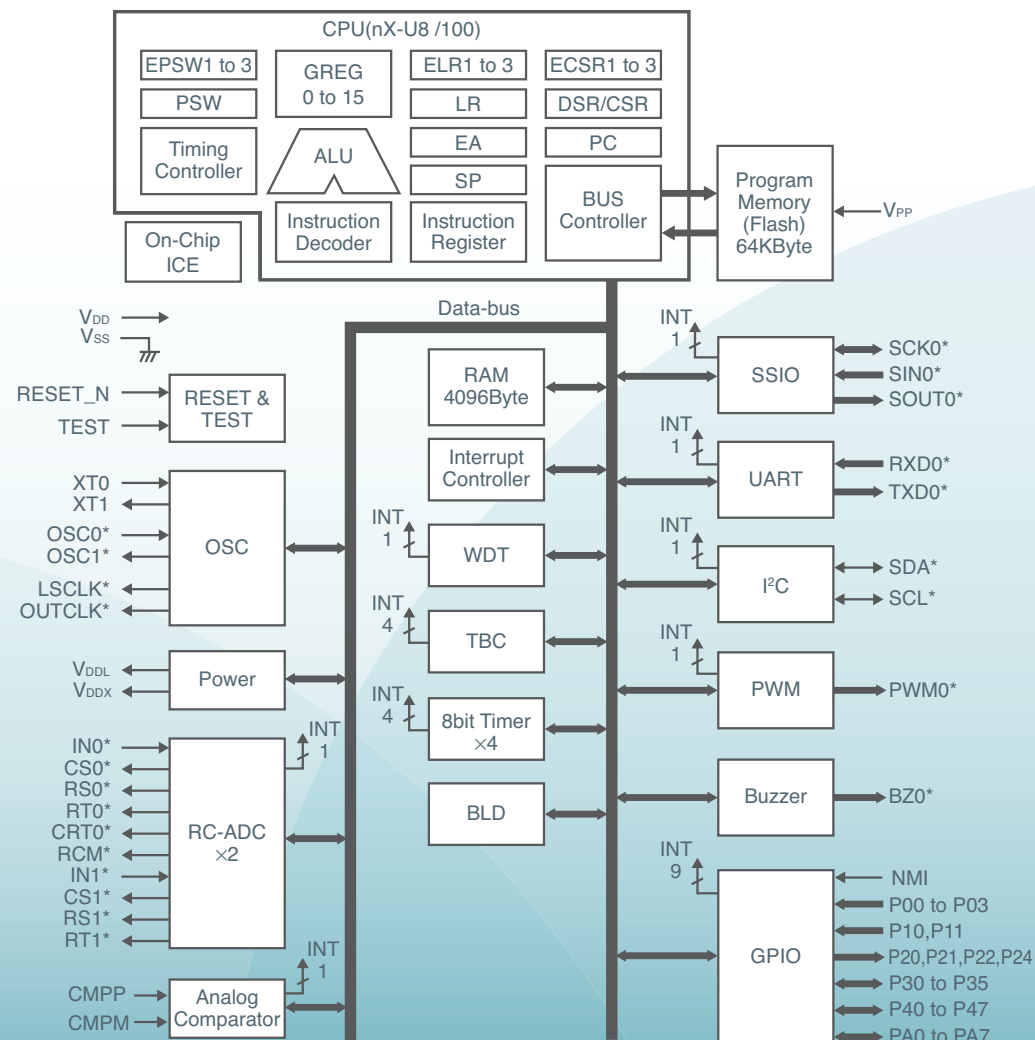
TQFP48

Actual size shown

Features

ROM		64KByte (Flash) (includes 1KByte test area)
RAM		4KByte
Ports (Includes Secondary Function)	Input	6
	Output	4
	Input/Output	22
A/D Converter		24bit RC oscillation type×2ch
Analog Comparator		Common mode input : 0.2V to VDD-1.0V Input offset : 50mV(typ.)
Serial I/F		UART×1, SSIO(SPI)×1, I ² C(master)×1
Timer	8bit Timer	4
	16bit PWM	1
	Others	TBC(Time Base Counter)×1, WDT×1
External Interrupt		5
Other Functions		Battery level detection, clock output, and more
Operating Frequency	High Speed	4.096MHz (internal PLL or external crystal/ceramic oscillator), 500kHz (internal RC oscillation)
	Low Speed	32.768kHz (crystal oscillation)
Operating Voltage		1.1V to 3.6V
Operating Temperature		ML610Q482 : -20°C to +70°C ML610Q482P : -40°C to +85°C
Current Consumption (Typ.)	At Standby	STOP mode : 0.2μA, HALT mode : 0.5μA
	During Operation	32kHz : 5μA (100% duty) 500kHz : 70μA (Internal RC oscillation) 4.096MHz : 830μA (Internal PLL)
Supply Form		Chip or TQFP48

Block diagram



* : Secondary function of port



Dot Matrix Type

ML610Q439 / ML610Q439P

Package



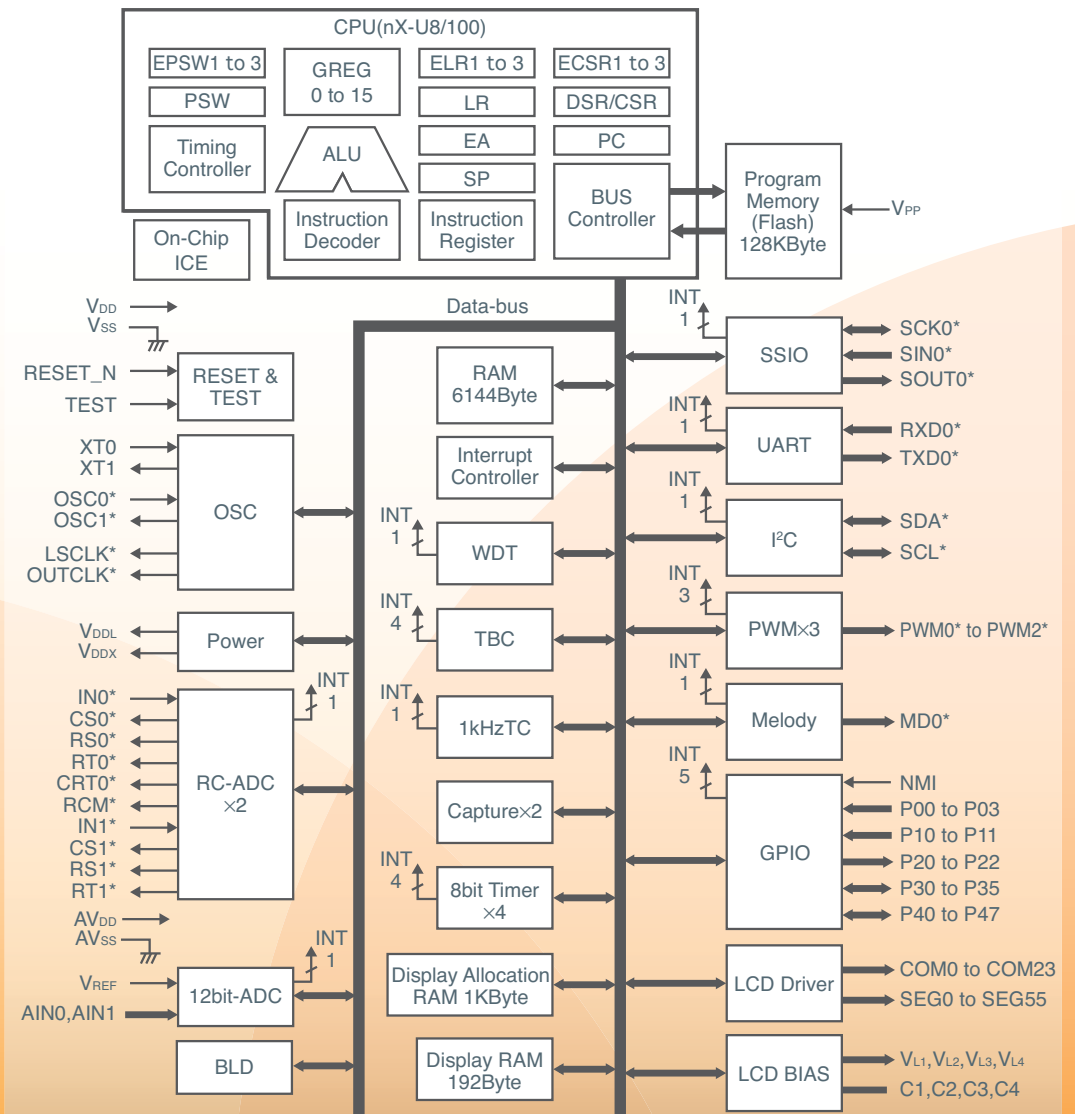
LQFP144

Actual size shown

Features

ROM		128KByte (Flash) (includes 1KByte test area)
RAM		7KByte (includes 1KByte LCD allocation register)
LCD Driver		Max.1024dot 64seg.x16com.
Ports (Includes Secondary Function)	Input	10
	Output	3
	Input/Output	20
A/D Converter		24bit RC oscillation type×2, 12bit successive approximation type×2
Serial I/F		UART×1, SSIO(SPI)×1, I ² C(master)×1
Timer	8bit Timer	4
	16bit PWM	16bit-PWM×3
	Others	TBC(Time Base Counter)×1, WDT×1, 1kHz Timer×1, Capture×2
External Interrupt		9
Other Functions		Buzzer/melody, clock output, battery level detection, and more
Operating Frequency	High Speed	4.096MHz (internal PLL or external crystal/ceramic oscillator), 2M/1M/500kHz (internal RC oscillation, option selection)
	Low Speed	32.768kHz (external crystal oscillation)
Operating Voltage		1.1V to 3.6V
Operating Temperature		ML610Q439 : -20°C to +70°C ML610Q439P : -40°C to +85°C
Current Consumption (Typ.)	At Standby	STOP mode : 0.15μA, HALT mode : 0.5μA
	During Operation	32kHz : 5μA (100% duty) 500kHz : 70μA (Internal RC oscillation) 4MHz : 800μA (Internal PLL)
Supply Form		Chip or LQFP144

Block diagram



* : Secondary function of port



Segment Type ML610Q409 / ML610Q409P

Package



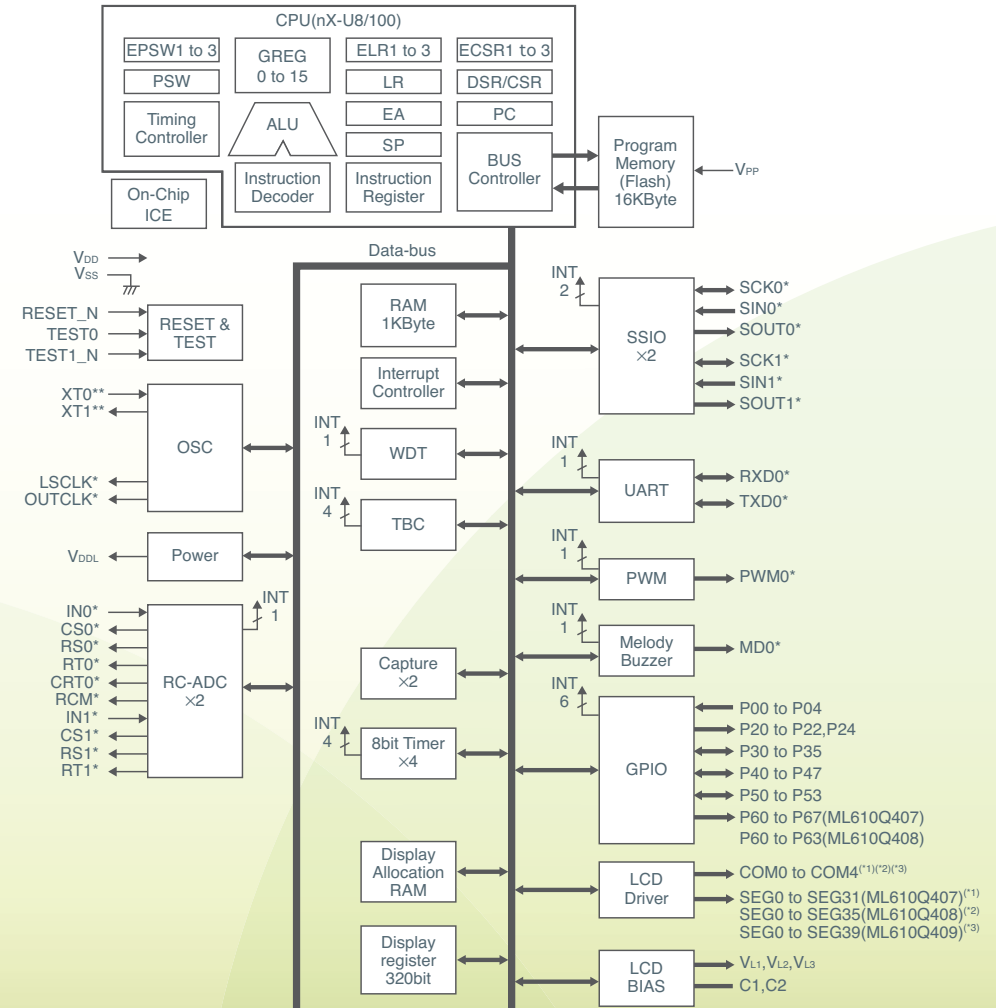
TQFP100

Actual size shown

Features

ROM		16KByte (Flash) (includes 1KByte test area)
RAM		1KByte
LCD Driver		Max.185dot 37seg.x5com.
Ports (Includes Secondary Function)	Input	5
	Output	4
	Input/Output	22
A/D Converter		16bit RC oscillation type×2
Serial I/F		UART×1, SSIO(SPI)×2
Timer	8bit Timer	4
	16bit PWM	16bit-PWM×1
	Others	TBC(Time Base Counter)×1, WDT×1, Capture×2
External Interrupt		13 (include 8bit-OR input)
Other Functions		Buzzer/melody, low-speed oscillation frequency correction (0.48ppm accuracy), clock output
Operating Frequency	High Speed	500kHz or 2MHz (internal RC oscillation)
	Low Speed	32.768kHz(crystal oscillation)
Operating Voltage		500kHz : 1.25V to 3.6V, 2MHz : 1.8V to 3.6V
Operating Temperature		ML610Q409 : -20°C to +70°C ML610Q409P : -40°C to +85°C
Current Consumption (Typ.)	At Standby	STOP mode : 0.4μA, HALT mode : 0.9μA
	During Operation	32kHz : 5μA, 500kHz : 70μA, 2MHz : 280μA
Supply Form		Chip or TQFP100

Block diagram



* : Secondary or tertiary function of port

⁽¹⁾ : Select between 29SEG × 5COM, 30SEG × 4COM, 31SEG × 3COM, or 32SEG × 2COM (via software)

⁽²⁾ : Select between 33SEG × 5COM, 34SEG × 4COM, 35SEG × 3COM, or 36SEG × 2COM (via software)

⁽³⁾ : Select between 37SEG × 5COM, 38SEG × 4COM, 39SEG × 3COM, or 40SEG × 2COM (via software)



Segment Type ML610401 / ML610401P

Package



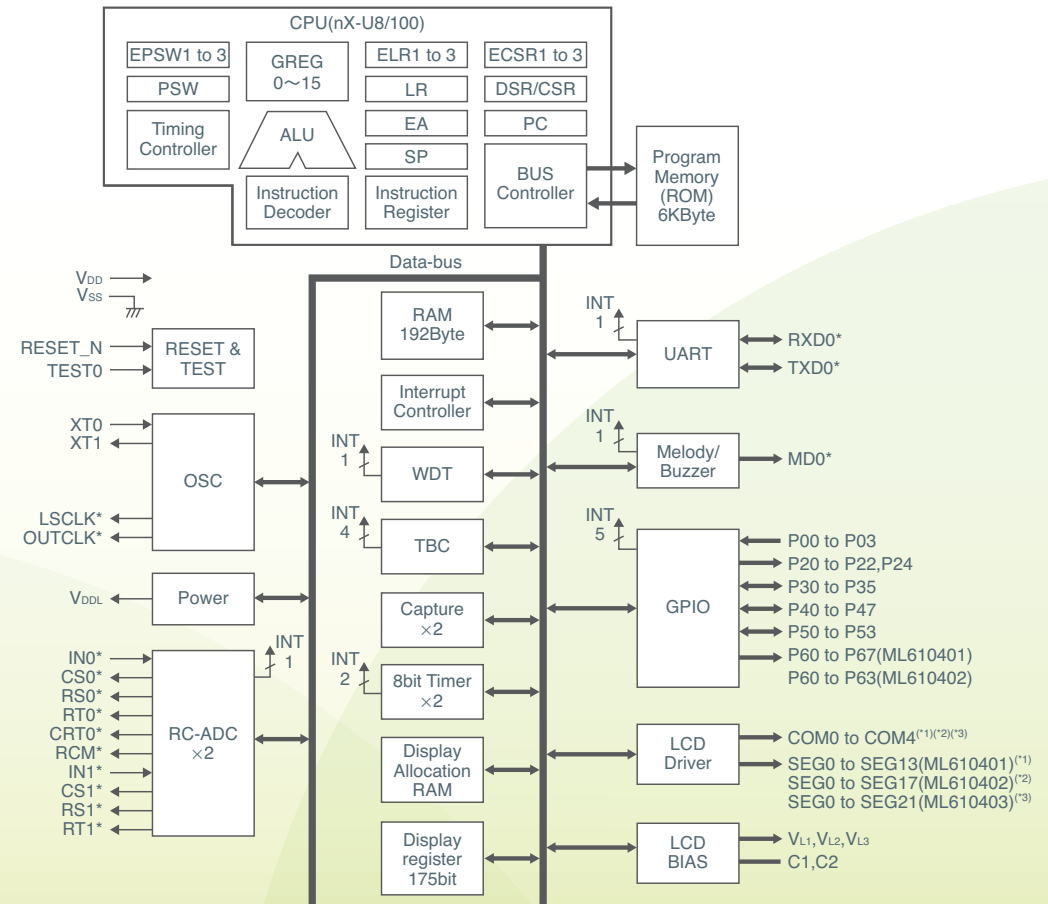
TQFP64

Actual size shown

Features

ROM		6KByte (Mask) (includes 1KByte test area)
RAM		192Byte
LCD Driver		Max.55dot 11seg.x5com.
Ports (Includes Secondary Function)	Input	4
	Output	12
	Input/Output	18
A/D Converter		16bit RC oscillation type×2ch
Serial I/F		UART×1
Timer	8bit Timer	2
	Others	TBC(Time Base Counter)×1, WDT×1, Capture×2
External Interrupt		8 (include 4bit-OR input)
Other Functions		Buzzer/melody, low-speed oscillation frequency correction (0.48ppm accuracy), clock output
Operating Frequency	High Speed	500kHz(internal RC oscillation)
	Low Speed	32.768kHz(crystal oscillation)
Operating Voltage		1.25V to 3.6V
Operating Temperature		ML610401 : -20°C to +70°C ML610401P : -40°C to +85°C
Current Consumption (Typ.)	At Standby	STOP mode : 0.3μA, HALT mode : 0.9μA
	During Operation	32kHz : 3μA, 500kHz : 50μA
Supply Form		Chip or TQFP64

Block diagram



* : Secondary function of port

^(*) : Select between 11SEG × 5COM, 12SEG × 4COM, 13SEG × 3COM, 14SEG × 2COM (via software)

⁽²⁾ : Select between 15SEG × 5COM, 16SEG × 4COM, 17SEG × 3COM, 18SEG × 2COM (via software)

⁽³⁾ : Select between 19SEG × 5COM, 20SEG × 4COM, 21SEG × 3COM, 22SEG × 2COM (via software)

Specifications

Standard Type

*1 : 4MHz generated via internal PLL / ceramic / crystal oscillation,
500kHz and 2MHz via RC oscillation,
32.768kHz via crystal oscillation, and 32kHz via RC oscillation
*2 : Low current consumption during Suspend (HALT) Mode via low-speed 32kHz crystal oscillation
Suspend (HALT) Mode : Low-speed oscillation - only a time-based counter and watchdog timer are active.
The CPU, LCD bias circuit, and high-speed operation are stopped. The internal regulator is ON.

*3 : Including secondary functions
*4 : Only master function can support fast mode (400kpbs) / standard mode (100kpbs)
*5 : Only the Master function supports Standard Mode (50kpbs)
*6 : No compatible chip select signals exist for 8bit / 16bit SPI BUS
*7 : Includes 256Byte test area
*8 : Includes 1KByte test area
*9 : 1KByte LCD RAM allocation included

Part No.	Operating Conditions					ROM/RAM		Functions/Features																Package	Chip Support
	Operating voltage (V)	Operating frequency ^{*1}	Minimum instruction execution time	Current consumption (Typ.@HALT) ^{*2}	Operating temperature (°C)	ROM capacity (Byte)	RAM capacity (Byte)	Port ^{*3}			8bit timer	1kHz timer	PWM	Capture	WDT	ADC(method)	Serial port			Supply voltage detection	LCD driver	Interrupt sources internal : external	Others		
								Input	Output	Input/Output							I ² C	SSIO ^{*6}	UART						
★ ML610Q486 / ML610Q486P	1.6 to 3.6	500kHz	2μs	15μA	-20 to +70 / -40 to +85	Flash 32K ^{*7}	1K	6	5	21	4 (16bit×2)	—	16bit×1	—	1	4 (Sequential)	1 ^{*5}	1	1	1	—	14 : 5	—	TQFP48-P-0707-0.50-K	○
★ ML610Q487 / ML610Q487P	1.8 to 3.8	1MHz / 32.768kHz	1μs 30.5μs	1.7μA	-20 to +70 / -40 to +85	Flash 48K ^{*7}	1.5K	8	4	24	8 (16bit×4)	—	16bit×2	—	1	—	1	1	2	—	—	19 : 6	Low speed frequency correction	TQFP48-P-0707-0.50-K	○
★ ML610Q488 / ML610Q488P	1.8 to 3.8	4MHz / 32.768kHz	0.25μs 30.5μs	1.7μA	-20 to +70 / -40 to +85	Flash 48K ^{*7}	1.5K	8	4	24	8 (16bit×4)	—	16bit×2	2	1	—	1	1	2	—	—	19 : 6	Low speed frequency correction	TQFP48-P-0707-0.50-K	○
★ ML610Q489 / ML610Q489P	1.8 to 3.8	4MHz / 31.25kHz (4MHz frequency division)	0.25μs 30.5μs	—	-20 to +70 / -40 to +85	Flash 48K ^{*7}	1.5K	8	4	24	8 (16bit×4)	—	16bit×2	2	1	—	1 ^{*4}	1	2	—	—	19 : 6	Low speed frequency correction	TQFP48-P-0707-0.50-K	○
NEW ML610Q482 / ML610Q482P	1.1 to 3.6	4.096MHz / 500kHz / 32.768kHz	0.244μs / 2μs / 30.5μs	0.5μA	-20 to +70 / -40 to +85	Mask 64K ^{*7}	4K	6	4	22	4 (16bit×2)	—	16bit×1	2	1	2 (RC oscillation)	1 ^{*4}	1	1	1	—	15 : 5	Low speed frequency correction/ Buzzer	TQFP48-P-0707-0.50-K	○
NEW ML610Q482 / ML610Q482P	1.1 to 3.6	4.096MHz / 500kHz / 32.768kHz	0.244μs / 2μs / 30.5μs	0.5μA	-20 to +70 / -40 to +85	Flash 64K ^{*7}	4K	6	4	22	4 (16bit×2)	—	16bit×1	2	1	2 (RC oscillation)	1	1	1	1	—	15 : 5	Low speed frequency correction/ Buzzer	TQFP48-P-0707-0.50-K	○

★ Under development

Dot Matrix Type

Part No.	Operating Conditions					ROM/RAM		Functions/Features																Package	Chip Support
	Operating voltage (V)	Operating frequency ^{*1}	Minimum instruction execution time	Current consumption (Typ.@HALT) ^{*2}	Operating temperature (°C)	ROM capacity (Byte)	RAM capacity (Byte)	Port ^{*3}			8bit timer	1kHz timer	PWM	Capture	WDT	ADC(method)	Serial port			Supply voltage detection	LCD driver	Interrupt sources internal : external	Others		
								Input	Output	Input/Output							I ² C	SSIO ^{*5}	UART						
ML610Q421 / ML610Q421P	1.1 to 3.6	4.096MHz / 500kHz / 32.768kHz	0.244μs / 2μs / 30.5μs	0.5μA	-20 to +70 / -40 to +85	Flash 32K ^{*7}	2K ^{*9}	6	3	22	4 (16bit×2)	1	16bit×1	2	1	2(RC oscillation) 2 (Sequential)	1 ^{*4}	1	1	1	Max. 400dot 50seg × 8com.	17 : 5	Low speed frequency correction/ Melody : Buzzer	TQFP120-P-1414-0.40-K	○
ML610Q422 /	1.1 to 3.6	4.096MHz / 500kHz / 32.768kHz	0.244μs / 2μs / 30.5μs	0.5μA	-20 to +70 / -40 to +85	Flash 32K ^{*7}	2K ^{*9}	6	3	14	4 (16bit×2)	1	16bit×1	2	1	2(RC oscillation) 2 (Sequential)	1 ^{*4}	1	1	1	Max. 800dot 50seg × 16com.	17 : 5	Low speed frequency correction/ Melody : Buzzer	TQFP120-P-1414-0.40-K	○
NEW ML610Q428P	1.1 to 3.6	4.096MHz / 2MHz / 32.768kHz	0.244μs / 2μs (@2MHz) / 30.5μs	0.5μA	-20 to +70 / -40 to +85	Flash 48K ^{*7}	4K ^{*9}	6	3	14	2 (16bit×1)	1	16bit×3	—	1	2(RC oscillation)	1 ^{*4}	1	1	1	Max. 1392dot 58seg × 24com.	20 : 5	RTC / Low speed frequency correction/ Melody : Buzzer	TQFP128-P-1414-0.40-K	○
NEW ML610Q429 / ML610Q429P	1.1 to 3.6	4.096MHz / 2MHz / 32.768kHz	0.244μs / 2μs (@2MHz) / 30.5μs	0.5μA	-20 to +70 / -40 to +85	Flash 48K ^{*7}	4K ^{*9}	10	3	20	2 (16bit×1)	1	16bit×3	—	1	2(RC oscillation)	1 ^{*4}	1	1	1	Max. 512dot 64seg × 8com.	20 : 9	RTC / Low speed frequency correction/ Melody : Buzzer	TQFP128-P-1414-0.40-K	○
ML610Q431	1.1 to 3.6	4.096MHz / 500kHz / 32.768kHz	0.244μs / 2μs / 30.5μs	0.5μA	-20 to +70	Flash 64K ^{*7}	3K ^{*9}	6	3	22	4 (16bit×2)	1	16bit×1	2	1	2(RC oscillation) 2 (Sequential)	1 ^{*4}	1	1	1	Max. 1024dot 64seg × 16com.	20 : 5	RTC / Low speed frequency correction/ Melody : Buzzer	LQFP144-P-2020-0.50-ZK	○
ML610Q432	1.1 to 3.6	4.096MHz / 500kHz / 32.768kHz	0.244μs / 2μs / 30.5μs	0.5μA	-20 to +70	Flash 64K ^{*7}	3K ^{*9}	6	3	14	4 (16bit×2)	1	16bit×1	2	1	2(RC oscillation) 2 (Sequential)	1 ^{*4}	1	1	1	Max. 1536dot 64seg × 24com.	20 : 5	RTC / Low speed frequency correction/ Melody : Buzzer	LQFP144-P-2020-0.50-ZK	○
NEW ML610Q435	1.1 to 3.6	4.096MHz / 500kHz / 32.768kHz	0.244μs / 2μs / 30.5μs	0.5μA	-20 to +70	Flash 96K ^{*7}	3K ^{*9}	6	3	22	4 (16bit×2)	1	16bit×1	2	1	2(RC oscillation) 2 (Sequential)	1 ^{*4}	1	1	1	Max. 1024dot 64seg × 16com.	20 : 5	RTC / Low speed frequency correction/ Melody : Buzzer	LQFP144-P-2020-0.50-ZK	○
NEW ML610Q436	1.1 to 3.6	4.096MHz / 500kHz / 32.768kHz	0.244μs / 2μs / 30.5μs	0.5μA	-20 to +70	Flash 96K ^{*7}	3K ^{*9}	6	3	14	4 (16bit×2)	1	16bit×1	2	1	2(RC oscillation) 2 (Sequential)	1 ^{*4}	1	1	1	Max. 1536dot 64seg × 24com.	20 : 5	RTC / Low speed frequency correction/ Melody : Buzzer	LQFP144-P-2020-0.50-ZK	○
NEW ML610Q438 / ML610Q438P	1.1 to 3.6	4.096MHz / 2MHz / 32.768kHz	0.244μs / 2μs (@2MHz) / 30.5μs	0.5μA	-20 to +70 / -40 to +85	Flash 128K ^{*7}	7K ^{*9}	10	3	20	4 (16bit×2)	1	16bit×3	2	1	2(RC oscillation) 2 (Sequential)	1 ^{*4}	1	1	1	Max. 1344dot 56seg × 24com.	23 : 9	Low speed frequency correction/ Melody : Buzzer	LQFP144-P-2020-0.50-ZK	○
NEW ML610Q439 / ML610Q439P	1.1 to 3.6	4.096MHz / 2MHz / 32.768kHz	0.244μs / 2μs (@2MHz) / 30.5μs	0.5μA	-20 to +70 / -40 to +85	Flash 128K ^{*7}	7K ^{*9}	10	3	20	4 (16bit×2)	1	16bit×3	2	1	2(RC oscillation) 2 (Sequential)	1 ^{*4}	1	1	1	Max. 1024dot 64seg × 16com.	23 : 9	Low speed frequency correction/ Melody : Buzzer	LQFP144-P-2020-0.50-ZK	○

Part No.	Operating Conditions					ROM/RAM		Functions/Features														Package	Chip Support		
	Operating voltage (V)	Operating frequency ^{*1}	Minimum instruction execution time	Current consumption (Typ. @HALT) ^{*2}	Operating temperature (°C)	ROM capacity (Byte)	RAM capacity (Byte)	Port ^{*3}			8bit timer	1kHz timer	PWM	Capture	WDT	ADC(method)	Serial port			Supply voltage detection	LCD driver			Interrupt sources internal : external	Others
								Input	Output	Input/Output							I ² C	SSIO ⁶	UART						
NEW ML610401 / ML610401P	1.25 to 3.6	500kHz / 32.768kHz	2μs / 30.5μs	0.9μA	-20 to +70 / -40 to +85	Mask 6K ^{*7}	192	4	12	18	2 (16bit×1)	—	—	2	1	2 (RC oscillation)	—	—	1	—	Max. 55dot 11seg × 5com.	10 : 8 (include 4bit-OR input)	Low speed frequency correction/ Melody : Buzzer	P-TQFP64-1010-0.50-ZK1	○
NEW ML610402 / ML610402P	1.25 to 3.6	500kHz / 32.768kHz	2μs / 30.5μs	0.9μA	-20 to +70 / -40 to +85	Mask 6K ^{*7}	192	4	8	18	2 (16bit×1)	—	—	2	1	2 (RC oscillation)	—	—	1	—	Max. 75dot 15seg × 5com.	10 : 8 (include 4bit-OR input)	Low speed frequency correction/ Melody : Buzzer	P-TQFP64-1010-0.50-ZK1	○
NEW ML610403 / ML610403P	1.25 to 3.6	500kHz / 32.768kHz	2μs / 30.5μs	0.9μA	-20 to +70 / -40 to +85	Mask 6K ^{*7}	192	4	4	18	2 (16bit×1)	—	—	2	1	2 (RC oscillation)	—	—	1	—	Max. 95dot 19seg × 5com.	10 : 8 (include 8bit-OR input)	Low speed frequency correction/ Melody : Buzzer	P-TQFP64-1010-0.50-ZK1	○
ML610404 / ML610404P	1.25 to 3.6	2MHz / 32.768kHz	0.5μs / 30.5μs	0.9μA	-20 to +70 / -40 to +85	Mask 8K ^{*7}	256	5	12	22	4 (16bit×2)	—	16bit×1	2	1	2 (RC oscillation)	—	2	1	—	Max. 105dot 21seg × 5com.	15 : 13 (include 8bit-OR input)	Low speed frequency correction/ Melody : Buzzer	P-TQFP80-1414-0.65-ZK	○
ML610405 / ML610405P	1.25 to 3.6	2MHz / 32.768kHz	0.5μs / 30.5μs	0.9μA	-20 to +70 / -40 to +85	Mask 8K ^{*7}	256	5	8	22	4 (16bit×2)	—	16bit×1	2	1	2 (RC oscillation)	—	2	1	—	Max. 125dot 25seg × 5com.	15 : 13 (include 8bit-OR input)	Low speed frequency correction/ Melody : Buzzer	P-TQFP80-1414-0.65-ZK	○
ML610406 / ML610406P	1.25 to 3.6	2MHz / 32.768kHz	0.5μs / 30.5μs	0.9μA	-20 to +70 / -40 to +85	Mask 8K ^{*7}	256	5	4	22	4 (16bit×2)	—	16bit×1	2	1	2 (RC oscillation)	—	2	1	—	Max. 145dot 29seg × 5com.	15 : 13 (include 8bit-OR input)	Low speed frequency correction/ Melody : Buzzer	P-TQFP80-1414-0.65-ZK	○
NEW ML610407 / ML610407P	1.25 to 3.6	2MHz / 32.768kHz	0.5μs / 30.5μs	0.9μA	-20 to +70 / -40 to +85	Mask 16K ^{*8}	1K	5	12	22	4 (16bit×2)	—	16bit×1	2	1	2 (RC oscillation)	—	2	1	—	Max. 145dot 29seg × 5com.	15 : 13 (include 8bit-OR input)	Low speed frequency correction/ Melody : Buzzer	P-TQFP100-1414-0.50-ZK	○
NEW ML610408 / ML610408P	1.25 to 3.6	2MHz / 32.768kHz	0.5μs / 30.5μs	0.9μA	-20 to +70 / -40 to +85	Mask 16K ^{*8}	1K	5	8	22	4 (16bit×2)	—	16bit×1	2	1	2 (RC oscillation)	—	2	1	—	Max. 165dot 33seg × 5com.	15 : 13 (include 8bit-OR input)	Low speed frequency correction/ Melody : Buzzer	P-TQFP100-1414-0.50-ZK	○
NEW ML610409 / ML610409P	1.25 to 3.6	2MHz / 32.768kHz	0.5μs / 30.5μs	0.9μA	-20 to +70 / -40 to +85	Mask 16K ^{*8}	1K	5	4	22	4 (16bit×2)	—	16bit×1	2	1	2 (RC oscillation)	—	2	1	—	Max. 185dot 37seg × 5com.	15 : 13 (include 8bit-OR input)	Low speed frequency correction/ Melody : Buzzer	P-TQFP100-1414-0.50-ZK	○
NEW ML610Q407 / ML610Q407P	1.25 to 3.6	2MHz / 32.768kHz	0.5μs / 30.5μs	0.9μA	-20 to +70 / -40 to +85	Flash 16K ^{*8}	1K	5	12	22	4 (16bit×2)	—	16bit×1	2	1	2 (RC oscillation)	—	2	1	—	Max. 145dot 29seg × 5com.	15 : 13 (include 8bit-OR input)	Low speed frequency correction/ Melody : Buzzer	P-TQFP100-1414-0.50-ZK	○
NEW ML610Q408 / ML610Q408P	1.25 to 3.6	2MHz / 32.768kHz	0.5μs / 30.5μs	0.9μA	-20 to +70 / -40 to +85	Flash 16K ^{*8}	1K	5	8	22	4 (16bit×2)	—	16bit×1	2	1	2 (RC oscillation)	—	2	1	—	Max. 165dot 33seg × 5com.	15 : 13 (include 8bit-OR input)	Low speed frequency correction/ Melody : Buzzer	P-TQFP100-1414-0.50-ZK	○
NEW ML610Q409 / ML610Q409P	1.25 to 3.6	2MHz / 32.768kHz	0.5μs / 30.5μs	0.9μA	-20 to +70 / -40 to +85	Flash 16K ^{*8}	1K	5	4	22	4 (16bit×2)	—	16bit×1	2	1	2 (RC oscillation)	—	2	1	—	Max. 185dot 37seg × 5com.	15 : 13 (include 8bit-OR input)	Low speed frequency correction/ Melody : Buzzer	P-TQFP100-1414-0.50-ZK	○
ML610Q411 / ML610Q411P	1.1 to 3.6	500kHz / 32.768kHz	2μs / 30.5μs	0.5μA	-20 to +70 / -40 to +85	Flash 16K ^{*7}	1K	6	3	22	4 (16bit×2)	1	16bit×1	2	1	2 (RC oscillation) 2 (Sequential)	^{*5} 1	1	1	1	Max. 144dot 36seg × 4com.	16 : 5	Low speed frequency correction/ Buzzer	TQFP120-P-1414-0.40-K	○
ML610Q412 / ML610Q412P	1.1 to 3.6	500kHz / 32.768kHz	2μs / 30.5μs	0.5μA	-20 to +70 / -40 to +85	Flash 16K ^{*7}	1K	6	3	14	4 (16bit×2)	1	16bit×1	2	1	2 (RC oscillation) 2 (Sequential)	^{*5} 1	1	1	1	Max. 176dot 44seg × 4com.	16 : 5	Low speed frequency correction/ Buzzer	TQFP120-P-1414-0.40-K	○
ML610Q415	1.1 to 3.6	500kHz	2μs	5.5μA	-20 to +70	Flash 16K ^{*7}	1K	6	3	22	4 (16bit×2)	1	16bit×1	2	1	2 (RC oscillation) 2 (Sequential)	^{*5} 1	1	1	1	Max. 144dot 36seg × 4com.	16 : 5	Low speed frequency correction/ Buzzer	TQFP120-P-1414-0.40-K	○

Target Products and Compatible Product Development Support Systems

	Target Products	Software Tools	Hardware Tools	
			Development Tool	Reference Board
Standard Type	ML610Q486 / ML610Q486P ML610Q487 / ML610Q487P ML610Q488 / ML610Q488P ML610Q489 / ML610Q489P ML610482 / ML610482P ML610Q482 / ML610Q482P	- Project management tool (IDEU8 integrated development environment) - Build tool - Debugging tool - Flash programming tool^{*11} - ROM code generation tool for code entry	μEASE ^{*10}	ML610Q486 Reference board ML610Q487 Reference board ML610Q488 Reference board ML610Q489 Reference board ML610Q482 Reference board ML610Q482 Reference board
	ML610Q421 / ML610Q421P ML610Q422 / ML610Q422P ML610Q428 / ML610Q428P ML610Q429 / ML610Q429P ML610Q431 ML610Q432 ML610Q435 ML610Q436 ML610Q438 / ML610Q438P ML610Q439 / ML610Q439P	- Project management tool (IDEU8 integrated development environment) - Build tool - Debugging tool - Flash programming tool^{*11} - Program development support tool for LCD control - ROM code generation tool for code entry	μEASE ^{*10}	ML610Q421 Reference board ML610Q422 Reference board ML610Q428 Reference board ML610Q429 Reference board ML610Q431 Reference board ML610Q432 Reference board ML610Q435 Reference board ML610Q436 Reference board ML610Q438 Reference board ML610Q439 Reference board
Segment Type with Built-In LCD Driver	ML610401 / ML610401P ML610402 / ML610402P ML610403 / ML610403P ML610404 / ML610404P ML610405 / ML610405P ML610406 / ML610406P ML610407 / ML610407P / ML610Q407 / ML610Q407P ML610408 / ML610408P / ML610Q408 / ML610Q408P ML610409 / ML610409P / ML610Q409 / ML610Q409P ML610Q411 / ML610Q411P ML610Q412 / ML610Q412P ML610Q415	<Required environment> - Windows [®] 2000/XP - Graphic adapter and display of SVGA (800×600) or more - At least 20MB of free hard disk space	μEASE ^{*10}	ML610Q407 Reference board ^{*12} ML610Q407 Reference board ^{*13} ML610Q407 Reference board ^{*14} ML610Q407 Reference board ^{*15} ML610Q407 Reference board ^{*16} ML610Q407 Reference board ^{*17} ML610Q407 Reference board ML610Q408 Reference board ML610Q409 Reference board ML610Q411 Reference board ML610Q412 Reference board ML610Q415 Reference board

- ^{*10}: All software except for MWμEASE is bundled in μEASE
^{*11}: All required μEASE units must be purchased when using MWμEASE
^{*12}: Setting the ML610Q407 reference board to ML610Q401 mode enables operation equivalent to the ML610401 Mask version.
^{*13}: Setting the ML610Q407 reference board to ML610Q402 mode enables operation equivalent to the ML610402 Mask version.
^{*14}: Setting the ML610Q407 reference board to ML610Q403 mode enables operation equivalent to the ML610403 Mask version.
^{*15}: Setting the ML610Q407 reference board to ML610Q404 mode enables operation equivalent to the ML610404 Mask version.
^{*16}: Setting the ML610Q407 reference board to ML610Q405 mode enables operation equivalent to the ML610405 Mask version.
^{*17}: Setting the ML610Q407 reference board to ML610Q406 mode enables operation equivalent to the ML610406 Mask version.

●U8 Core, nX-U8/100 Core is an LAPIS Semiconductor's original 8bit CPU of RISC method. ●IDEU8 is an LAPIS Semiconductor's project management tool for program development. ●CCU8 is an LAPIS Semiconductor's C compiler for program development. ●RASU8 is an LAPIS Semiconductor's assembler for program development. ●RLU8 is an LAPIS Semiconductor's linker for program development. ●LIBU8 is an LAPIS Semiconductor's librarian (library generation tool) for program development. ●OHU8 is an LAPIS Semiconductor's object converter for program development. ●FWμEASE is an LAPIS Semiconductor's flash writing tool. ●HTU8 is an LAPIS Semiconductor's ROM code generation tool for code entry (flash writing). ●DTU8 is an LAPIS Semiconductor's debug tool for program development. ●μEASE is an LAPIS Semiconductor's on-chip debug emulator. ●MWμEASE is an LAPIS Semiconductor's flash writing tool (for multi-writing). ●MACU8 is an LAPIS Semiconductor's assemble package for program development. ●Windows® 2000 / Windows® XP / Windows® Vista are registered trademarks of Microsoft Corporation USA in the US and other countries.

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